

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
1	BRS	L1	128079	multilayer	USPA T; EPO; JPO; DER WEN T; USOC R	2002/12/29 16:25	
2	BRS	L2	293	1 and (core adj substrate)	USPA T; EPO; JPO; DER WEN T; USOC R	2002/12/29 17:31	
3	BRS	L3	0	2 and (bonding adj plate)	USPA T; EPO; JPO; DER WEN T; USOC R	2002/12/29 16:40	
4	BRS	L4	167	2 and resin	USPA T; EPO; JPO; DER WEN T; USOC R	2002/12/29 16:40	
5	BRS	L5	11	4 and capacitor	USPA T; EPO; JPO; DER WEN T; USOC R	2002/12/29 16:48	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
6	BRS	L6	42	2 and opening	USPAT; EPO; JPO; DER WEN T; USOCR	2002/12/29 16:47	
7	BRS	L7	6	6 and capacitor	USPAT; EPO; JPO; DER WEN T; USOCR	2002/12/29 16:48	
8	IS&R	L8	2	("6153290").PN.	USPAT; EPO; JPO; DER WEN T; USOCR	2002/12/29 16:52	
9	BRS	L9	13	("4109296"   "4811164"   "4899118"   "5055966"   "5315486"   "5384434"   "5387888"   "5416277"   "5708559"   "5708570"   "5757611"   "5814366"   "6021050").PN.	USPAT	2002/12/29 16:49	
10	BRS	L10	5	6153290.URPN.	USPAT	2002/12/29 16:51	
11	IS&R	L11	2	("5565706").PN.	USPAT; EPO; JPO; DER WEN T; USOCR	2002/12/29 16:59	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
12	BRS	L12	7	("4322778"   "4672421"   "5049978"   "5280192"   "5315486"   "5331203"   "5391917").PN.	USPA T	2002/12/29 16:52	
13	BRS	L13	10	5565706.URPN.	USPA T	2002/12/29 18:02	
14	BRS	L14	12	("4544989"   "4993148"   "5014111"   "5206712"   "5262351"   "5300812"   "5315486"   "5508561"   "5545589"   "5565706"   "5757072"   "5786628").PN.	USPA T	2002/12/29 16:55	
15	BRS	L15	6	5875100.URPN.	USPA T	2002/12/29 16:56	
16	BRS	L16	30	2 and (thermosetting adj resin)	USPA T; EPO; JPO; DER WEN T; USOC R	2002/12/29 17:31	
17	BRS	L17	41	2 and thermosetting	USPA T; EPO; JPO; DER WEN T; USOC R	2002/12/29 17:06	
18	BRS	L18	24	17 and bond\$3	USPA T; EPO; JPO; DER WEN T; USOC R	2002/12/29 17:06	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
19	BRS	L19	1821	(core adj substrate)	USPA T; EPO; JPO; DER WEN T; USOC R	2002/12/29 17:31	
20	BRS	L20	109	19 and (thermosetting adj resin)	USPA T; EPO; JPO; DER WEN T; USOC R	2002/12/29 17:32	
21	BRS	L21	30	19 and (resin adj layers)	USPA T	2002/12/29 18:06	
22	IS&R	L22	2	("5937493").PN.	USPA T; EPO; JPO; DER WEN T; USOC R	2002/12/29 18:04	
23	BRS	L23	1	"3326718".PN.	USPA T	2002/12/29 18:05	
24	BRS	L25	1	5937493.URPN.	USPA T	2002/12/29 18:05	
25	BRS	L26	69	19 and (resin adj layer)	USPA T	2002/12/29 18:06	
26	BRS	L27	372	19 and laminat\$3	USPA T	2002/12/29 18:06	
27	BRS	L28	239	27 and resin	USPA T	2002/12/29 18:07	
28	BRS	L29	66	28 and (opening or recess or aperture)	USPA T	2002/12/29 18:07	
29	BRS	L30	15	29 and capacitor	USPA T	2002/12/29 18:10	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
30	BRS	L31	18	("5103288"   "5498467"   "5526449"   "5600342"   "5731073"   "5766979"   "5830565"   "5886413"   "5886535"   "5896038"   "5966022"   "5966593"   "5990850"   "6046076"   "6114087"   "6177181"   "6216469"   "6255601").PN.	USPA T	2002/12/29 18:09	
31	BRS	L32	156	multilayer adj wiring adj board	USPA T	2002/12/29 18:12	
32	BRS	L33	116	32 and resin	USPA T	2002/12/29 18:35	
33	BRS	L34	5	("4617586"   "5027253"   "6038122"   "6094336"   "6252761").PN.	USPA T	2002/12/29 18:18	
34	BRS	L35	19	("3326718"   "3624895"   "3665346"   "3699011"   "3949275"   "4237522"   "4328531"   "4342143"   "4349862"   "4453176"   "4460938"   "4682414"   "4705917"   "4729061"   "4744008"   "4751126"   "4890192"   "4910638"   "4958258").PN.	USPA T	2002/12/29 18:19	
35	BRS	L36	35	5027253.URPN.	USPA T	2002/12/29 18:21	
36	BRS	L37	12	19 and (resin adj insulating adj layer)	USPA T	2002/12/29 18:40	
37	BRS	L38	5	("4710593"   "4791238"   "5675299"   "5956843"   "6042685").PN.	USPA T	2002/12/29 18:36	
38	BRS	L39	4	("4816323"   "5346750"   "5766670"   "6010768").PN.	USPA T	2002/12/29 18:37	
39	BRS	L40	2	("5590016"   "5636099").PN.	USPA T	2002/12/29 18:39	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
40	IS&R	L41	155	(361/763).CCLS.	USPA T; EPO; JPO; DER WEN T; USOC R	2002/12/29 18:40	
41	BRS	L42	6	("4750246"   "5103283"   "5438305"   "5539358"   "5798557"   "6133674").PN.	USPA T	2002/12/29 18:41	

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DB4: USPAT, EPO, JP, DE, WENT, US, OCR

Highlight all hit terms initially

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L1: (2939) multilayer adj circuit adj board  
 L2: (157) 1 and interlayer  
 L3: (5) 2 and capacitor  
 L4: (42) 4490429.URPN.  
 L5: (6) 2 and cavity  
 L6: (127929) multilayer  
 L7: (8904) 6 and interlayer  
 L8: (2868) 7 and resin  
 L9: (1396) 8 and (substrate or (core adj substrate))  
 L10: (424) 9 and (opening or openings or cavity or cavities)  
 L11: (59) 10 and capacitor  
 L12: (5) ("4617586" | "5027253" | "6038122" | "6094336" | "6252761").PN.  
 L13: (19) ("3326718" | "3624895" | "3665346" | "3699011" | "3949275" | "42  
 L14: (35) 5027253.URPN.  
 L15: (283) 428/\$.ccls. and (core adj substrate)  
 L16: (6) 15 and capacitor  
 L17: (1817) (core adj substrate)  
 L18: (391) 17 and (opening or openings or cavity or cavities)  
 L19: (31) 18 and (capacitor or capacitors)  
 L20: (635) 8 and (opening or openings or cavity or cavities)  
 L21: (95) 20 and (capacitor or capacitors)  
 L22: (7) ("4322778" | "4672421" | "5049978" | "5280192" | "5315486" | "533  
 L23: (10) 5565706.URPN.  
 L24: (248) [257/725].CCLS.

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 (0) H.sub2.0

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BRSTerm All S&R term Advanced Text HTML

U	Document ID	Issue Date	Page	Title	Current OR	Current XRe	Retrieval	Inventor	S	C	P	2	3	4	5
1	<input type="checkbox"/> <input checked="" type="checkbox"/> US 6495915	20021217	17	Flip chip package of monolithic microwave integr. R1	257/728	257/684; 257/691;	257/725	Hsieh, Tsung-Ying et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>					
2	<input type="checkbox"/> <input checked="" type="checkbox"/> US 6495913	20021217	15	Semiconductor clamped_stack_assembly.	257/718	257/685;	257/725	Gruning, Horst	<input checked="" type="checkbox"/>	<input type="checkbox"/>					
3	<input type="checkbox"/> <input checked="" type="checkbox"/> US 6483188	20021119	6	Rf integrated circuit layout	257/728	257/165; 257/206;	257/725	Yue, Chik Patrick et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>					
4	<input type="checkbox"/> <input checked="" type="checkbox"/> US 6476484	20021105	7	Heat sink dissipator for antenna_to_thickness chan.	257/718	257/706; 257/712;	257/725	Liang, Robert	<input checked="" type="checkbox"/>	<input type="checkbox"/>					
5	<input type="checkbox"/> <input checked="" type="checkbox"/> US 6472748	20021029	9	System and method for providing MMIC seal	257/728	219/660; 219/668;	257/725	Calvert, Carl Edward	<input checked="" type="checkbox"/>	<input type="checkbox"/>					
6	<input type="checkbox"/> <input checked="" type="checkbox"/> US 6472723	20021029	12	Substrate contacts and shielding devices in a semic.	257/659	257/503; 257/508;	257/725	Jarstad, Tomas et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>					
7	<input type="checkbox"/> <input checked="" type="checkbox"/> US 6469377	20021022	12	Semiconductor device	257/686	257/725;	257/725	Kondo, Yoichiro	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>					

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